

Claims

- [c1] An integrated circuit probe card comprising:
a circuit board consisting a plurality of laminated boards and having an upper surface and a bottom surface, comprising:
a plurality of testing pads provided on the upper surface and separated by a second pitch, and being able to be electrically connected to a test machine directly; and
a plurality of conductive wires provided inside the circuit board for connecting the testing pads to the bottom surface; and
a plurality of probes separated by a first pitch and being electrically connected to the conductive wires, wherein the first pitch is smaller than the second pitch.
- [c2] The integrated circuit probe card of Claim 1, wherein the circuit board is constituted by tightly stacking up a plurality of laminated boards.
- [c3] The integrated circuit probe card of Claim 1, wherein the circuit board can further comprises a plurality of electronic devices provided on the upper surface for processing testing signals.

- [c4] The integrated circuit probe card of Claim 1, wherein the first pitch is smaller than 400 micrometer.
- [c5] The integrated circuit probe card of Claim 1, wherein the plurality of probes are directly in contact with the conductive wires.
- [c6] The integrated circuit probe card of Claim 1, wherein the first pitch is approximately the same as the pitch between signal pads of an integrated circuit device under test.